

FDP55N06/FDPF55N06

60V N-Channel MOSFET

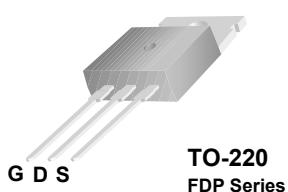
Features

- 55A, 60V, $R_{DS(on)} = 0.022 \Omega$ @ $V_{GS} = 10 V$
- Low gate charge (typical 30 nC)
- Low Crss (typical 60 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

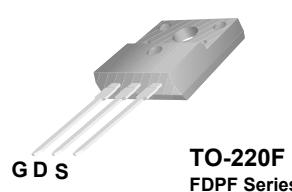
Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

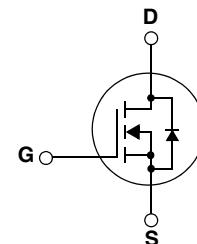
This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficient switched mode power supplies, active power factor correction, electronic lamp ballast based on half bridge topology.



TO-220
FDP Series



TO-220F
FDPF Series



Absolute Maximum Ratings

$T_C = 25^\circ C$ unless otherwise noted

Symbol	Parameter	FDP55N06	FDPF55N06	Units
V_{DSS}	Drain-Source Voltage	60		V
I_D	Drain Current - Continuous ($T_C = 25^\circ C$)	55	55 *	A
	- Continuous ($T_C = 100^\circ C$)	34.8	34.8 *	A
I_{DM}	Drain Current - Pulsed	(Note 1)	220	A
V_{GSS}	Gate-Source Voltage		± 25	V
E_{AS}	Single Pulsed Avalanche Energy	(Note 2)	480	mJ
I_{AR}	Avalanche Current	(Note 1)	55	A
E_{AR}	Repetitive Avalanche Energy	(Note 1)	11.4	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	4.5	V/ns
P_D	Power Dissipation ($T_C = 25^\circ C$)	114	48	W
	- Derate above $25^\circ C$	0.9	0.4	W/ $^\circ C$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	$^\circ C$
T_L	Maximum lead temperature for soldering purposes, 1/8 Δ from case for 5 seconds		300	$^\circ C$

* Drain current limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	FDP55N06	FDPF55N06	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.1	2.58	$^\circ C/W$
$R_{\theta JS}$	Thermal Resistance, Case-to-Sink Typ.	0.5	--	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	62.5	$^\circ C/W$

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDP55N06	FDP55N06	TO-220			50
FDPF55N06	FDPF55N06	TO-220F			50

Electrical Characteristics

$T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$	60	--	--	V
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, Referenced to 25°C	--	0.05	--	$\text{V}/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 60 \text{ V}$, $V_{GS} = 0 \text{ V}$	--	--	1	μA
		$V_{DS} = 48 \text{ V}$, $T_C = 150^\circ\text{C}$	--	--	10	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 20 \text{ V}$, $V_{DS} = 0 \text{ V}$	--	--	100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -20 \text{ V}$, $V_{DS} = 0 \text{ V}$	--	--	-100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250 \mu\text{A}$	2.0	--	4.0	V
$R_{DS(\text{on})}$	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}$, $I_D = 27.5 \text{ A}$	--	0.018	0.022	Ω
g_{FS}	Forward Transconductance	$V_{DS} = 25 \text{ V}$, $I_D = 27.5 \text{ A}$	(Note 4)	--	33	--
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS} = 25 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 1.0 \text{ MHz}$	--	1160	1510	pF
C_{oss}	Output Capacitance		--	375	490	pF
C_{rss}	Reverse Transfer Capacitance		--	60	90	pF
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 30 \text{ V}$, $I_D = 55 \text{ A}$, $R_G = 25 \Omega$	--	30	65	ns
t_r	Turn-On Rise Time		--	130	265	ns
$t_{d(off)}$	Turn-Off Delay Time		--	70	150	ns
t_f	Turn-Off Fall Time		--	95	195	ns
Q_g	Total Gate Charge	$V_{DS} = 48 \text{ V}$, $I_D = 55 \text{ A}$, $V_{GS} = 10 \text{ V}$	--	30	37	nC
Q_{gs}	Gate-Source Charge		--	6.5	--	nC
Q_{gd}	Gate-Drain Charge		--	7.5	--	nC
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain-Source Diode Forward Current		--	--	55	A
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	220	A
V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}$, $I_S = 55 \text{ A}$	--	--	1.4	V
t_{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}$, $I_S = 55 \text{ A}$, $dI_F / dt = 100 \text{ A}/\mu\text{s}$	--	40	--	ns
Q_{rr}	Reverse Recovery Charge		(Note 4)	--	55	--

Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. $L = 5.6\text{mH}$, $I_{AS} = 55\text{A}$, $V_{DD} = 50\text{V}$, $R_G = 25 \Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 55\text{A}$, $di/dt \leq 200\text{A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
4. Pulse Test : Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$
5. Essentially independent of operating temperature

Typical Performance Characteristics

Figure 1. On-Region Characteristics

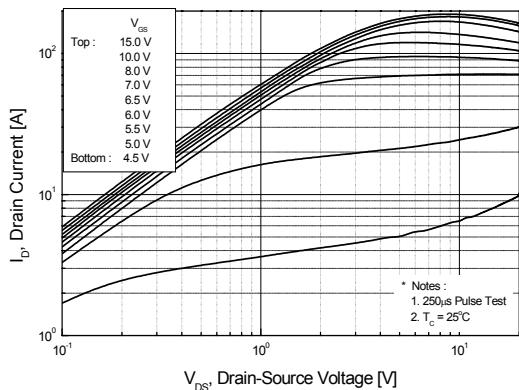


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

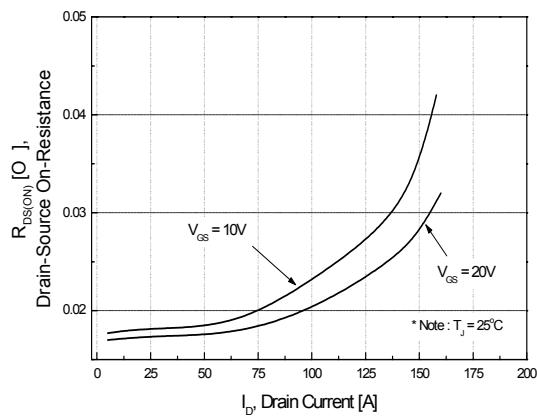


Figure 5. Capacitance Characteristics

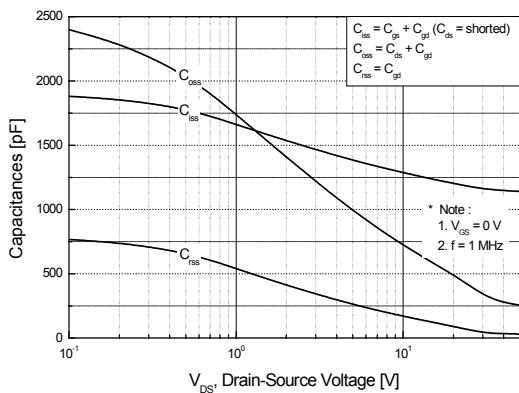


Figure 2. Transfer Characteristics

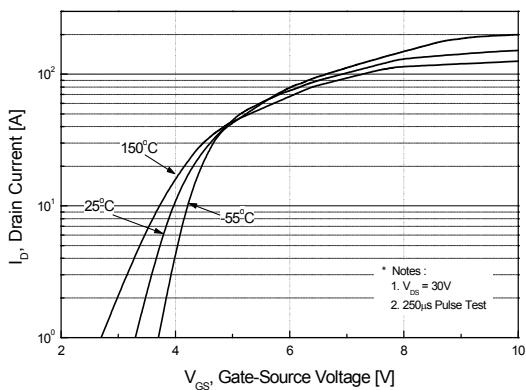


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

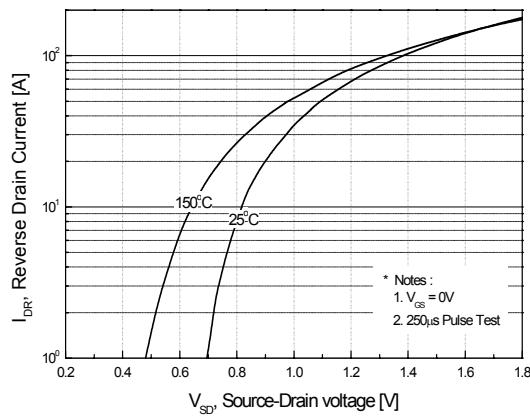


Figure 6. Gate Charge Characteristics

